XPX150N10TU

100V N-Channel Enhancement Mode Power MOSFET

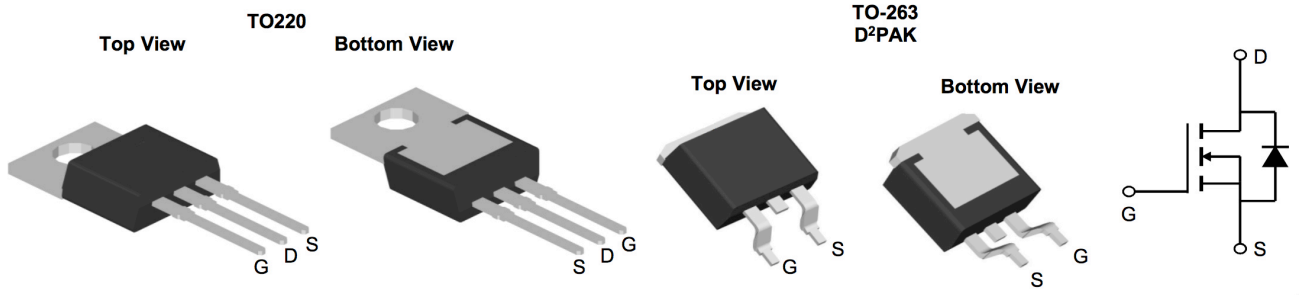
Features

- 100V/150A,
  $R_{DS\ (ON)}$ =3.2mΩ(Typ.)@V_{GS}=10V
- Advanced HEFET® Technology
- Ultra Low On-Resistance
- Excellent Q_gx$R_{DS(on)}$ Product
- 100% avalanche tested
- 175°C Operating Temperature
- Lead Free and Green Devices Available (RoHS Compliant)

Applications

- Motor Drives
- Uninterruptible Power Supplies
- DC/DC converter
- General Purpose Applications

- **Pin Configurations**



Absolute Maximum Ratings

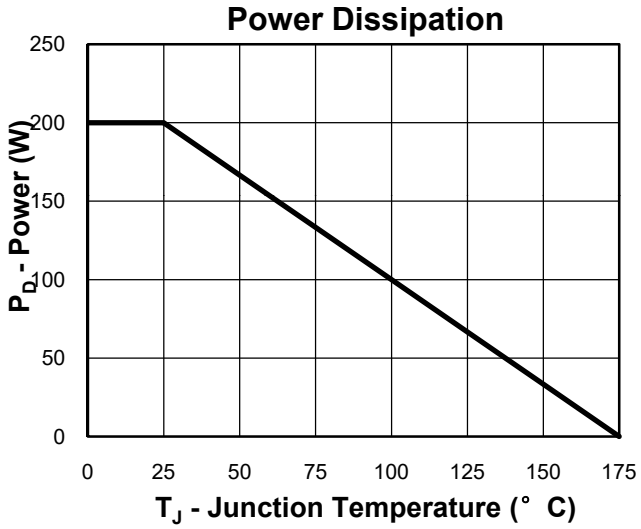
Symbol	Parameter		Rating	Unit
Common Ratings (T_C=25°C Unless Otherwise Noted)				
V_{DSS}	Drain-Source Voltage		100	V
V_{GSS}	Gate-Source Voltage		±25	
T_J	Maximum Junction Temperature		175	°C
T_{STG}	Storage Temperature Range		-55 to 175	°C
I_S	Diode Continuous Forward Current	T_C=25°C	75	A
Mounted on Large Heat Sink				
I_{DP} ①	300μs Pulse Drain Current Tested	T_C=25°C	600	A
I_D ②	Continuous Drain Current(V_{GS}=10V)	T_C=25°C	150	A
		T_C=100°C	106	
P_D	Maximum Power Dissipation	T_C=25°C	200	W
		T_C=100°C	100	
$R_{\theta JC}$	Thermal Resistance-Junction to Case		0.75	°C/W
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient		62.5	°C/W
Drain-Source Avalanche Ratings				
E_{AS} ③	Avalanche Energy, Single Pulsed		440	mJ

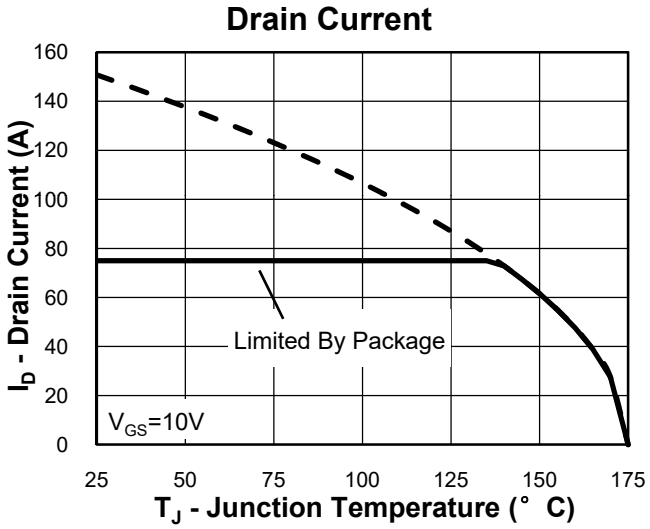
Electrical Characteristics (T_C=25°C Unless Otherwise Noted)

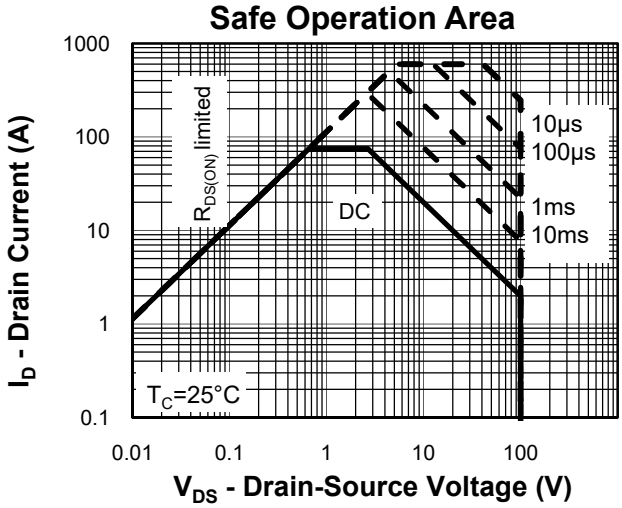
• 100V/150A	Parameter	Test Condition	XPX150N10TU			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=250μA	100			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=100V, V_{GS}=0V			1	μA
		T_J=125°C			30	
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=250μA	2		4	V
I_{GSS}	Gate Leakage Current	V_{GS}=±25V, V_{DS}=0V			±100	nA
$R_{DS(ON)}$④	Drain-Source On-state Resistance	V_{GS}=10V, I_{DS}=75A		3.2	4	mΩ
Diode Characteristics						
V_{SD}④	Diode Forward Voltage	I_{SD}=75A, V_{GS}=0V			1.2	V
t_{rr}	Reverse Recovery Time	I_{SD}=75A, dI_{SD}/dt=100A/μs		36		ns
Q_{rr}	Reverse Recovery Charge			28		nC
Dynamic Characteristics⑤						
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V,F=1MHz		2.1		Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=50V, Frequency=1.0MHz		3650		pF
C_{oss}	Output Capacitance			750		
C_{rss}	Reverse Transfer Capacitance			27		
$t_{d(ON)}$	Turn-on Delay Time	V_{DD}=50V,I_{DS}=75A, V_{GEN}=10V,R_G=4.7Ω		24		ns
t_r	Turn-on Rise Time			13		
$t_{d(OFF)}$	Turn-off Delay Time			49		
t_f	Turn-off Fall Time			17		
Gate Charge Characteristics⑤						
Q_g	Total Gate Charge	V_{DS}=80V, V_{GS}=10V, I_{DS}=75A		87		nC
Q_{gs}	Gate-Source Charge			23		
Q_{gd}	Gate-Drain Charge			15		

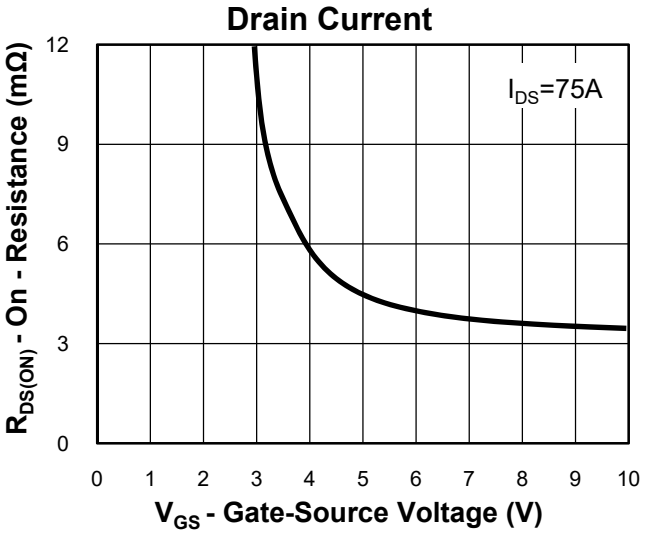
Notes:
①Pulse width limited by safe operating area.
②Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 75A.
③Limited by T_{Jmax}, I_{AS} =42A, V_{DD} = 60V, R_G = 50Ω , Starting T_J = 25°C.
④Pulse test;Pulse width≤300μs, duty cycle≤2%.
⑤Guaranteed by design, not subject to production testing.

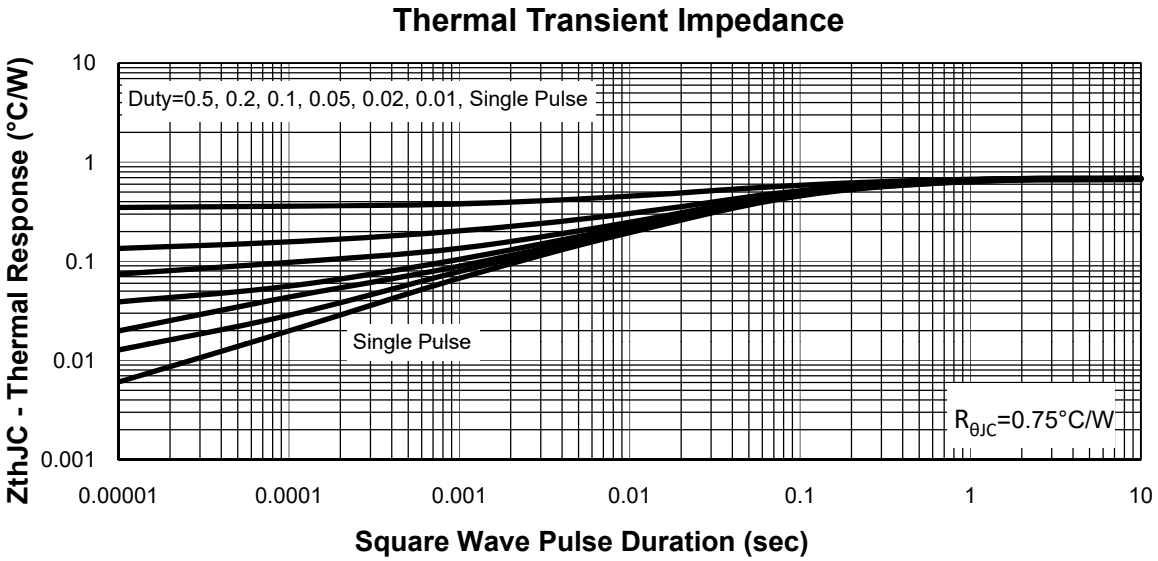
Typical Characteristics





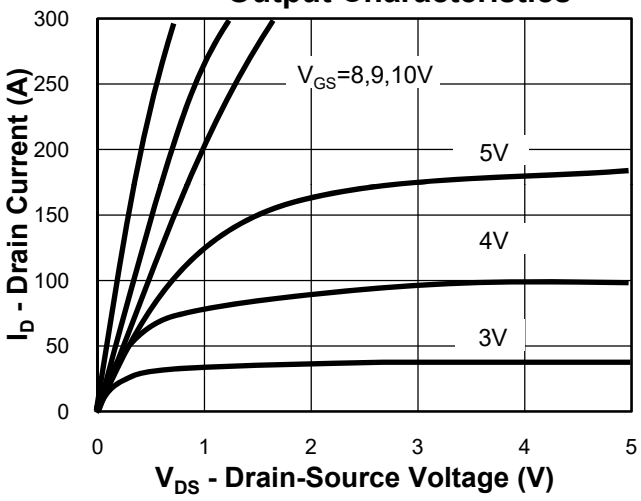




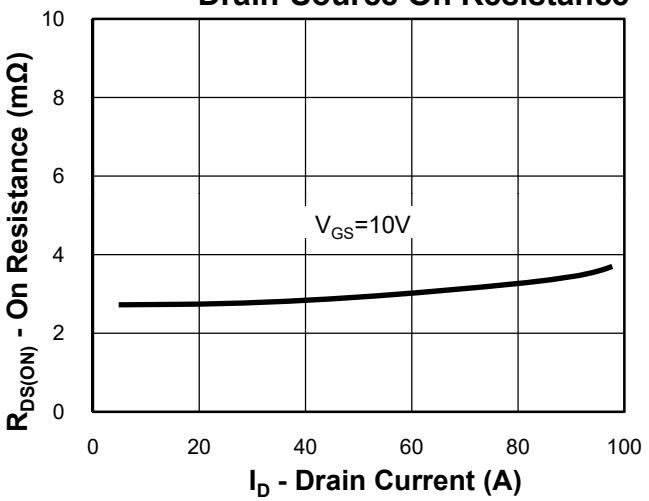


Typical Characteristics

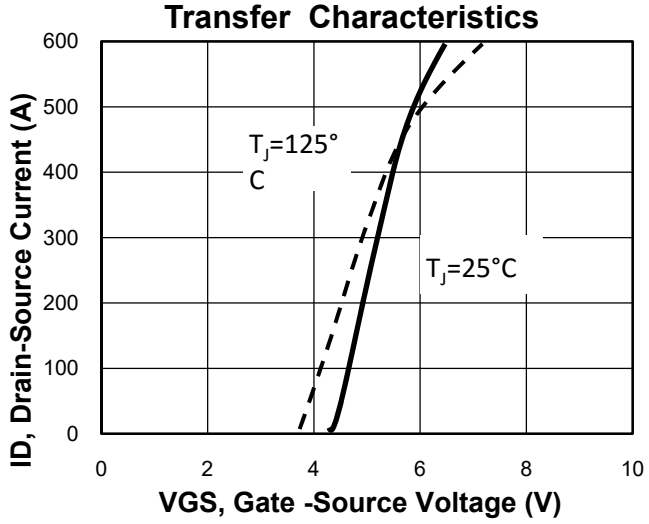
Output Characteristics



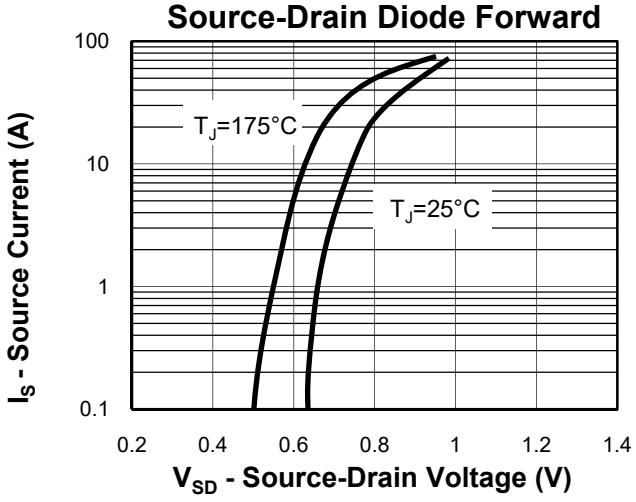
Drain-Source On Resistance



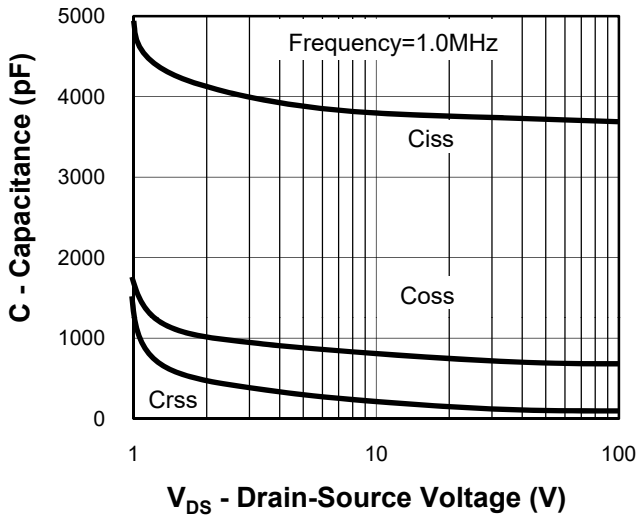
Transfer Characteristics



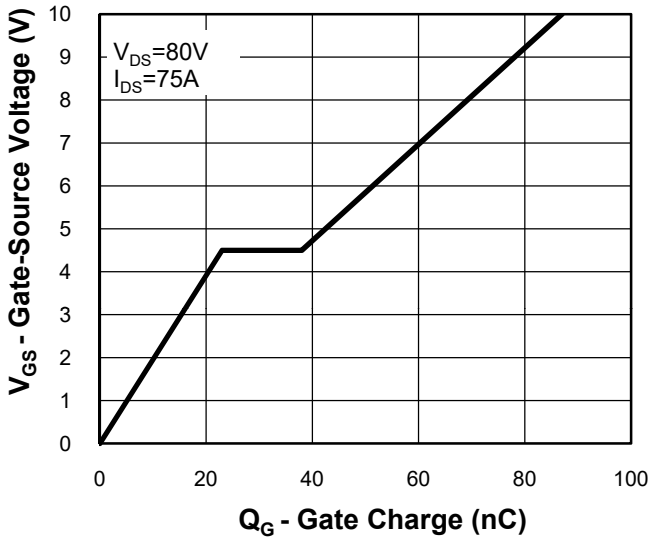
Source-Drain Diode Forward



Capacitance

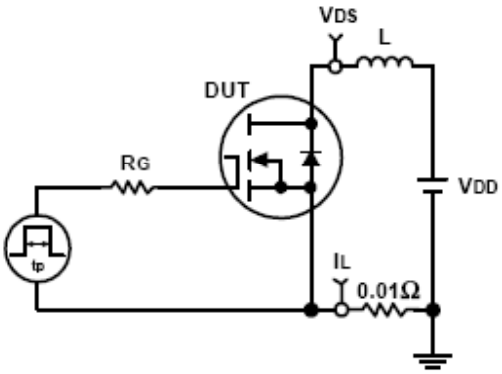


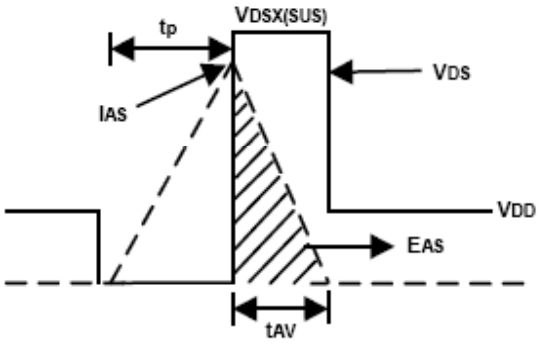
Gate Charge



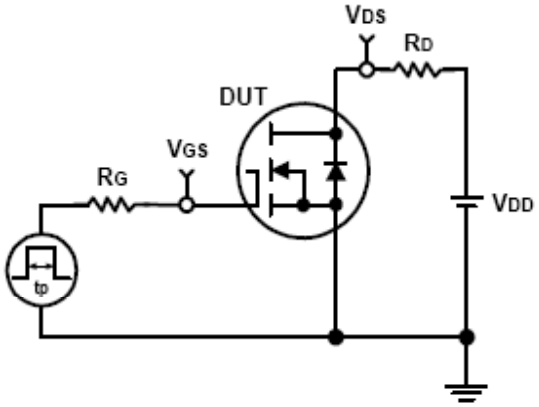
Avalanche Test Circuit and Waveforms

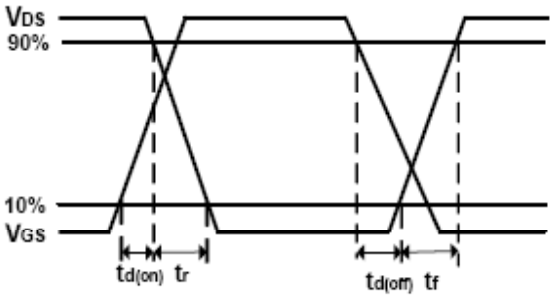
• 100V/150A,





Switching Time Test Circuit and Waveforms





Ordering and Marking Information

Device	Marking	Package	Packaging	Quantity	Reel Size	Tape width
XPX150N10TU	XPX150N10TU	TO220	Tube	50	-	-

Package Information

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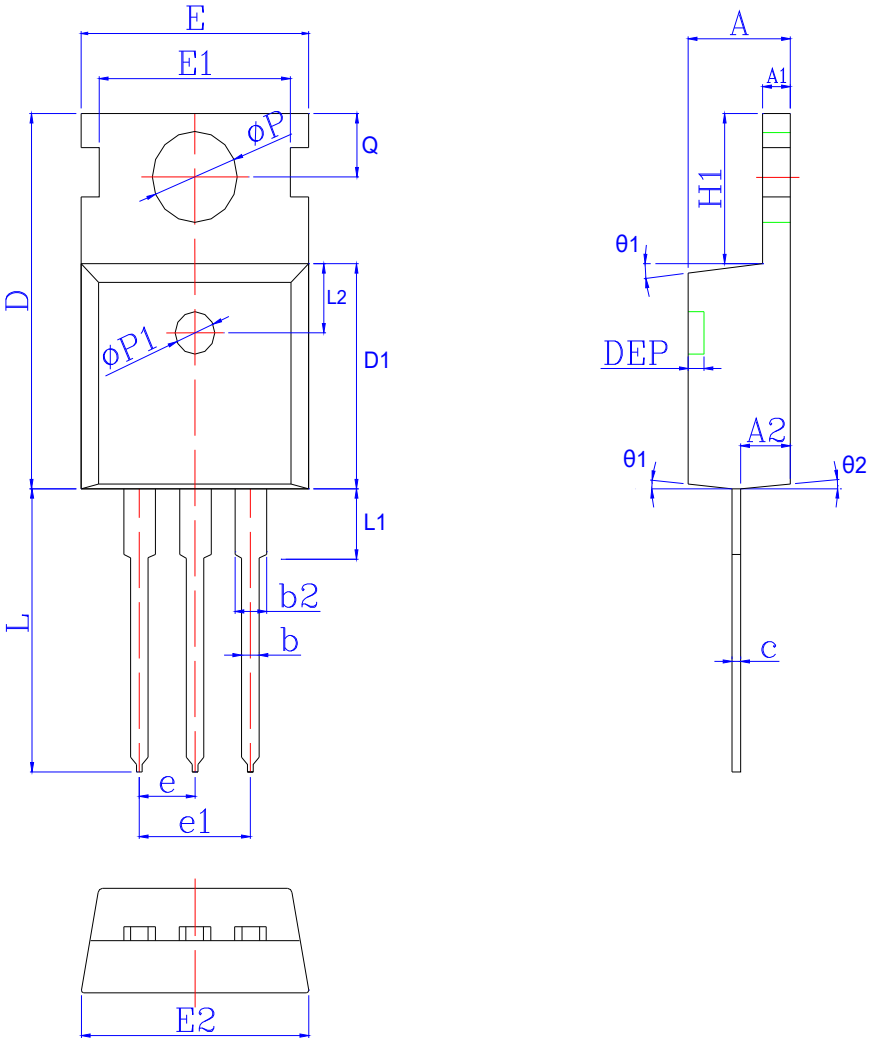
TO220



SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	4.30	4.50	4.70	0.169	0.177	0.185	Φp1	1.40	1.50	1.60	0.055	0.059	0.063
A1	1.15	1.30	1.40	0.045	0.051	0.055	e	2.54 BSC			0.10 BSC		
A2	1.90	2.25	2.60	0.075	0.089	0.102	e1	5.08 BSC			0.20 BSC		
b	0.60	0.80	1.00	0.024	0.031	0.039	H1	6.35	6.50	6.80	0.250	0.256	0.268
b2	1.17	1.28	1.72	0.046	0.050	0.068	L	12.70	13.18	13.65	0.500	0.519	0.537
c	0.40	0.50	0.60	0.016	0.020	0.024	L1	*	*	3.95	*	*	0.156
D	15.40	15.70	16.00	0.606	0.618	0.630	L2	2.50 REF			0.098 REF		
D1	8.96	9.21	9.46	0.353	0.363	0.372	Φp	3.50	3.60	3.75	0.138	0.142	0.148
DEP	*	*	0.30	*	*	0.012	Q	2.70	2.80	3.20	0.106	0.110	0.126
E	9.66	9.97	10.28	0.380	0.393	0.405	θ1	5°	7°	9°	5°	7°	9°
E1	*	8.70	*	*	0.343	*	θ2	1°	3°	5°	1°	3°	5°
E2	9.80	10.00	10.20	0.386	0.394	0.402							

Flow (wave) soldering (solder dipping)

Product	Peak Temperature	Dipping Time
Pb device	245℃±5℃	5sec±1sec
Pb-Free device	260℃+0/-5℃	5sec±1sec

This integrated circuit can be damaged by ESD UniverChip Corporation recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedure can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

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